



Material Content Data Sheet



Sales Product Name		BFN 27 E6327		Issued		25. September 2017			
MA#		MA000049632							
Package		PG-SOT23-3-3		Weight*		8.71 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.003	0.04		388		
	noble metal	gold	7440-57-5	0.013	0.15		1504		
	inorganic material	silicon	7440-21-3	0.160	1.84	2.03	18359	20251	
leadframe	non noble metal	nickel	7440-02-0	1.142	13.12		131218		
	non noble metal	iron	7439-89-6	1.578	18.12	31.24	181205	312423	
wire	noble metal	gold	7440-57-5	0.017	0.19	0.19	1913	1913	
	encapsulation	organic material	carbon black	1333-86-4	0.089	1.02		10175	
		inorganic material	antimonytrioxide	1309-64-4	0.133	1.53		15263	
		plastics	brominated resin	-	0.166	1.91		19078	
		plastics	epoxy resin	-	1.384	15.90		158986	
		inorganic material	silicondioxide	60676-86-0	3.765	43.23	63.59	432441	635943
leadfinish	non noble metal	tin	7440-31-5	0.150	1.72	1.72	17188	17188	
plating	noble metal	silver	7440-22-4	0.107	1.23	1.23	12282	12282	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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